



BSS138AKQB-Q

60 V, N-channel Trench MOSFET

2 September 2024

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1110D-3 (SOT8015) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Extended temperature range $T_j = 175\text{ °C}$
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection
- Side wettable flanks for optical solder inspection
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

4. Quick reference data

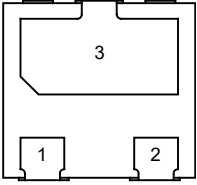
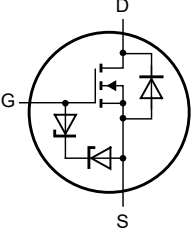
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$		-	-	60	V
V_{GS}	gate-source voltage			-20	-	20	V
I_D	drain current	$V_{GS} = 10\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	-	340	mA
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 100\text{ mA}; T_j = 25\text{ °C}$		-	2.1	2.8	Ω

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2 .

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 Transparent top view DFN1110D-3 (SOT8015)	 017aaa255
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BSS138AKQB-Q	DFN1110D-3	plastic, leadless extremely thin small outline package with side-wettable flanks (SWF); 3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body	SOT8015

7. Marking

Table 4. Marking codes

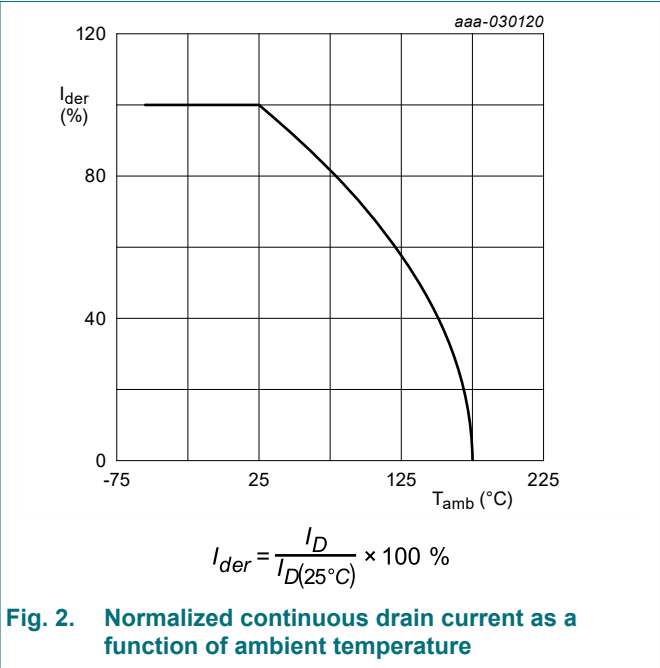
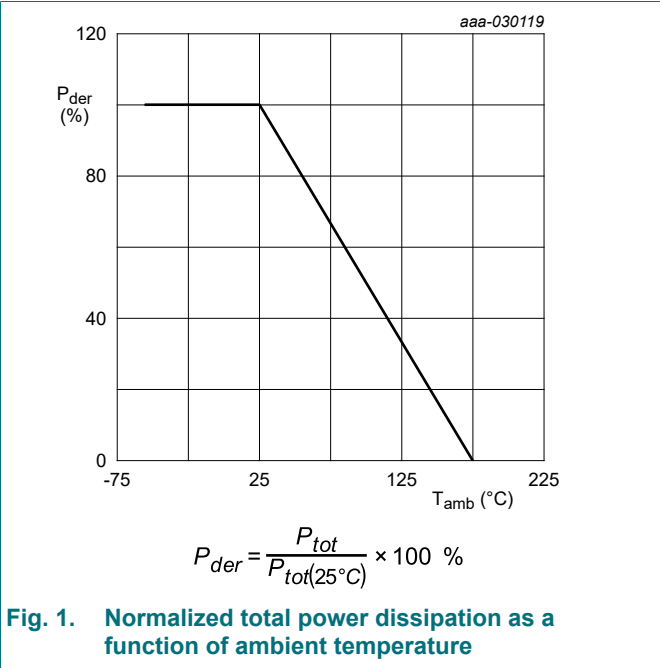
Type number	Marking code
BSS138AKQB-Q	QL

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	60	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C	[1]	-	340	mA
		V _{GS} = 10 V; T _{amb} = 100 °C	[1]	-	240	mA
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs		-	4	A
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	490	mW
			[1]	-	760	mW
		T _{sp} = 25 °C		-	6.9	W
T _j	junction temperature			-55	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	340	mA
ESD maximum rating						
V _{ESD}	electrostatic discharge voltage	HBM		-	500	V
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{j(initial)} = 25 °C; I _D = 20 mA; DUT in avalanche (unclamped)		-	6.6	mJ

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



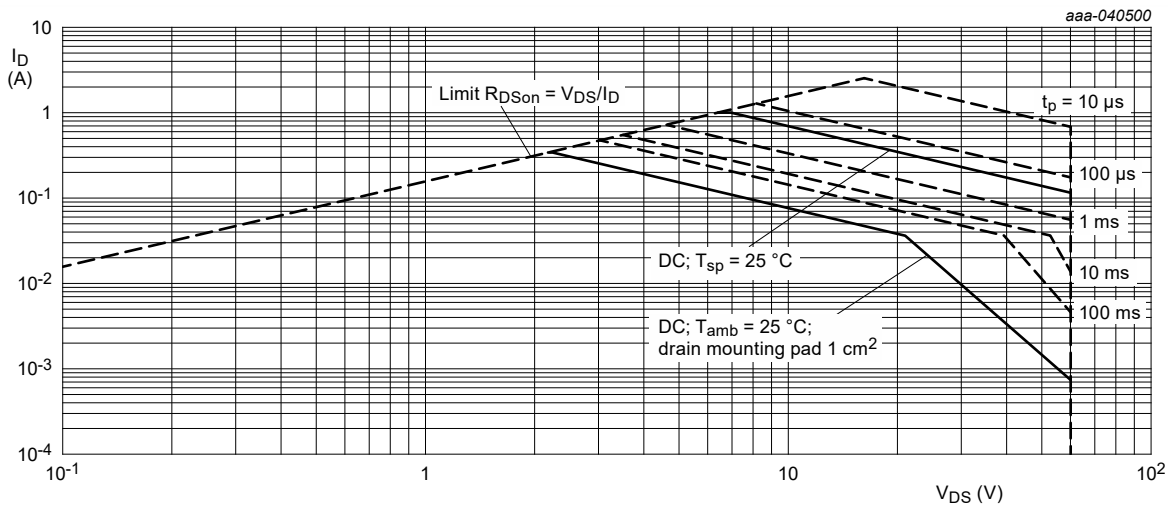


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	265	305	K/W
			[2]	-	171	197	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	17	22	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

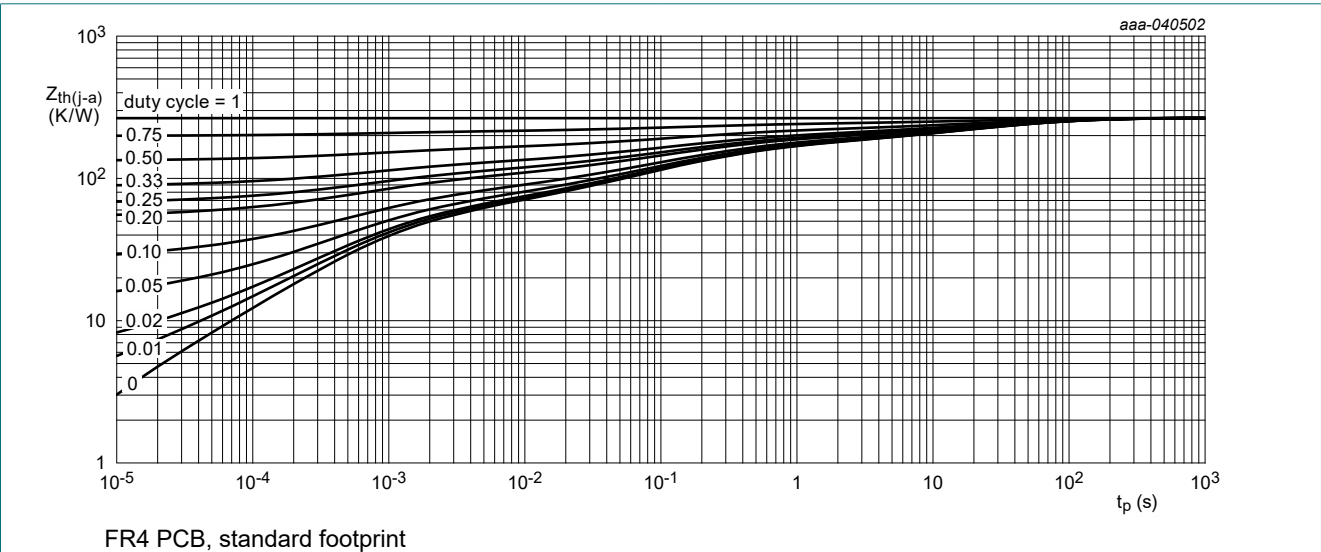


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

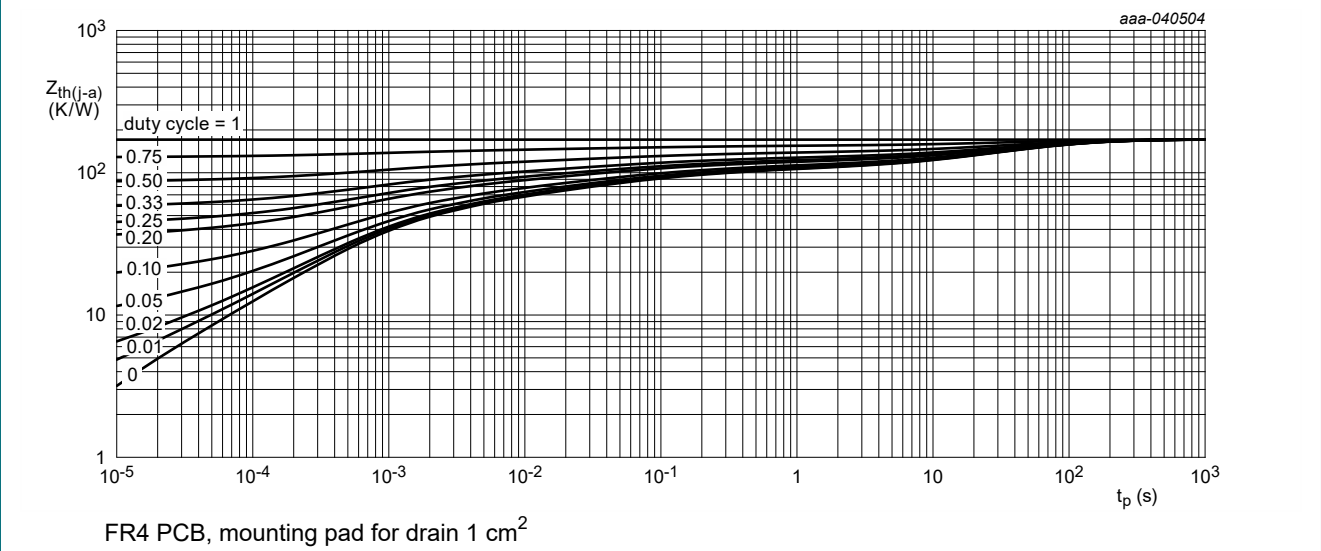


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _J = 25 °C		60	-	-	V
V _{GSth}	gate-source threshold voltage	I _D = 250 μA; V _{DS} = V _{GS} ; T _J = 25 °C		0.8	1.1	1.5	V
I _{DSS}	drain leakage current	V _{DS} = 60 V; V _{GS} = 0 V; T _J = 25 °C		-	-	500	nA
		V _{DS} = 60 V; V _{GS} = 0 V; T _J = 125 °C		-	-	5	μA
I _{GSS}	gate leakage current	V _{GS} = 20 V; V _{DS} = 0 V; T _J = 25 °C		-	-	10	μA
		V _{GS} = -20 V; V _{DS} = 0 V; T _J = 25 °C		-	-	-10	μA
		V _{GS} = 10 V; V _{DS} = 0 V; T _J = 25 °C		-	-	1	μA
		V _{GS} = -10 V; V _{DS} = 0 V; T _J = 25 °C		-	-	-1	μA
		V _{GS} = 4.5 V; V _{DS} = 0 V; T _J = 25 °C		-	-	500	nA
		V _{GS} = -4.5 V; V _{DS} = 0 V; T _J = 25 °C		-	-	-500	nA
		R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 100 mA; T _J = 25 °C		-	2.1
V _{GS} = 10 V; I _D = 100 mA; T _J = 175 °C		-		4.8	6.4	Ω	
V _{GS} = 4.5 V; I _D = 50 mA; T _J = 25 °C		-		2.5	3.6	Ω	
V _{GS} = 2.5 V; I _D = 10 mA; T _J = 25 °C		-		3.4	12	Ω	
g _{fs}	forward transconductance	V _{DS} = 5 V; I _D = 100 mA; T _J = 25 °C		-	0.3	-	S
Dynamic characteristics							
Q _{G(tot)}	total gate charge	V _{DS} = 30 V; I _D = 100 mA; V _{GS} = 10 V; T _J = 25 °C		-	0.21	0.315	nC
Q _{GS}	gate-source charge			-	0.022	-	nC
Q _{GD}	gate-drain charge			-	0.051	-	nC
C _{iss}	input capacitance	V _{DS} = 30 V; f = 1 MHz; V _{GS} = 0 V; T _J = 25 °C		-	9	-	pF
C _{oss}	output capacitance			-	1.8	-	pF
C _{rss}	reverse transfer capacitance			-	1.1	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = 30 V; I _D = 100 mA; V _{GS} = 10 V; R _{G(ext)} = 6 Ω; T _J = 25 °C		-	1	-	ns
t _r	rise time			-	1	-	ns
t _{d(off)}	turn-off delay time			-	2	-	ns
t _f	fall time			-	3	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = 210 mA; V _{GS} = 0 V; T _J = 25 °C		-	1	1.6	V
t _{rr}	reverse recovery time	I _S = 210 mA; dI _S /dt = -100 A/μs; V _{GS} = 0 V; V _{DS} = 30 V; T _J = 25 °C		-	7	-	ns
Q _r	recovered charge			-	1	-	nC

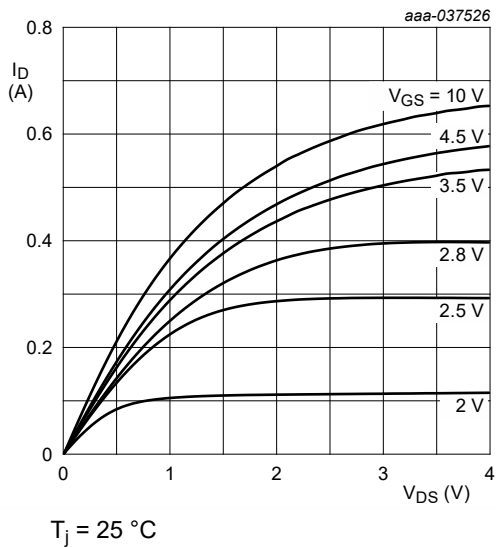


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

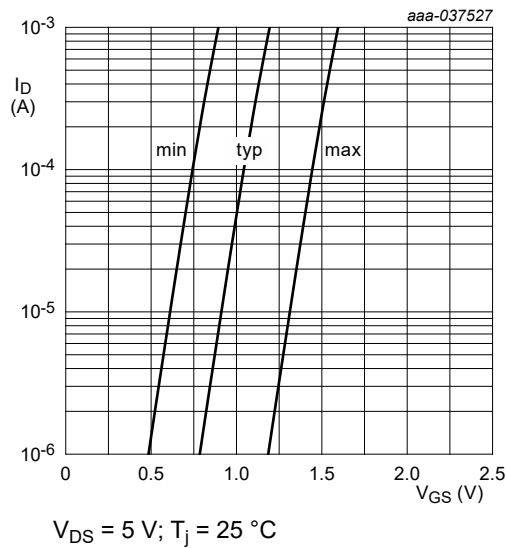


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

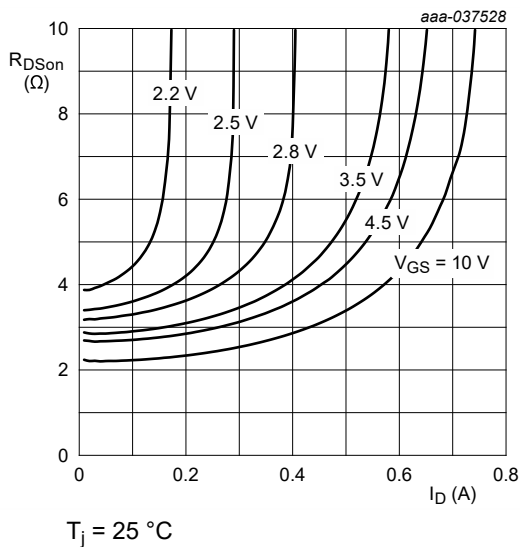


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

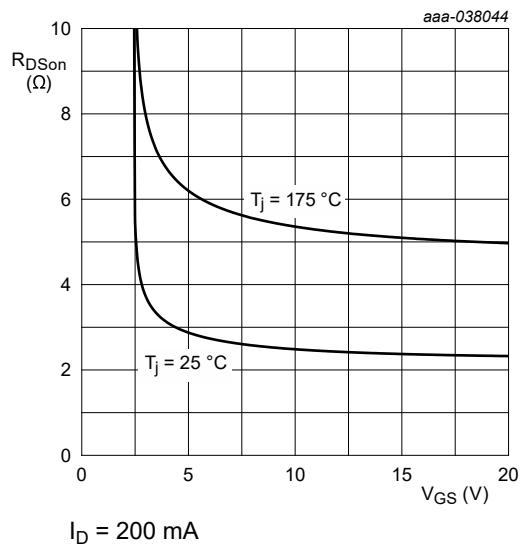


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

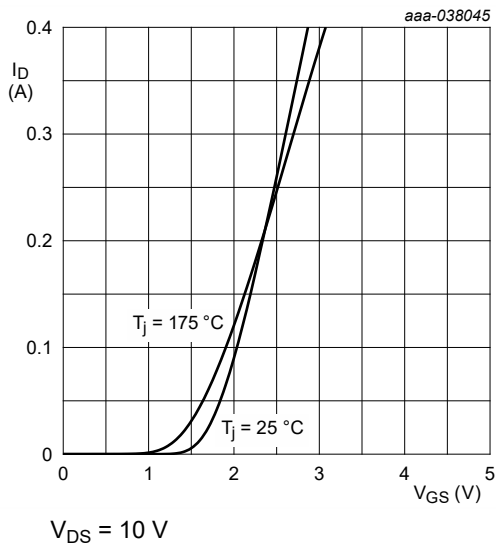


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

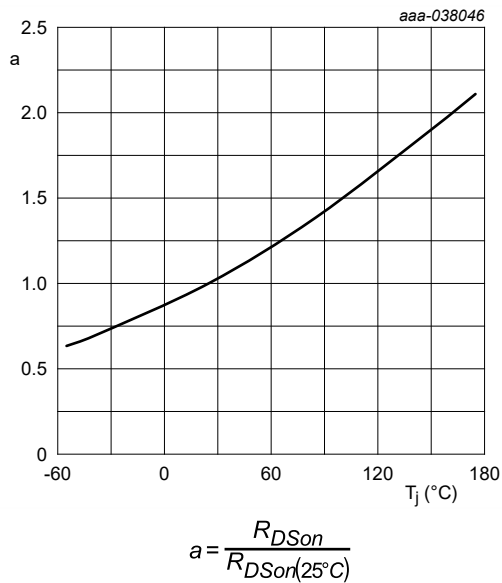


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

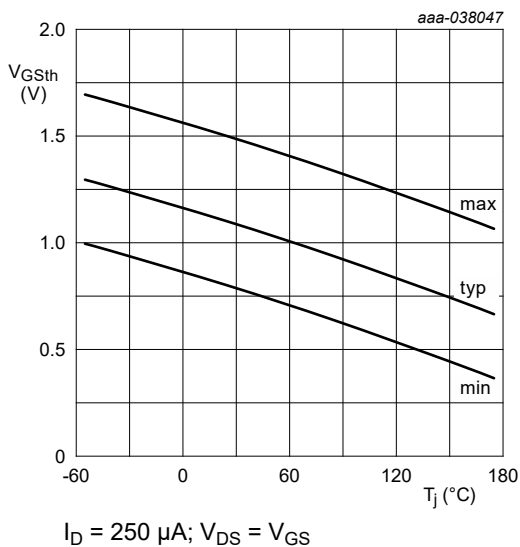


Fig. 12. Gate-source threshold voltage as a function of junction temperature

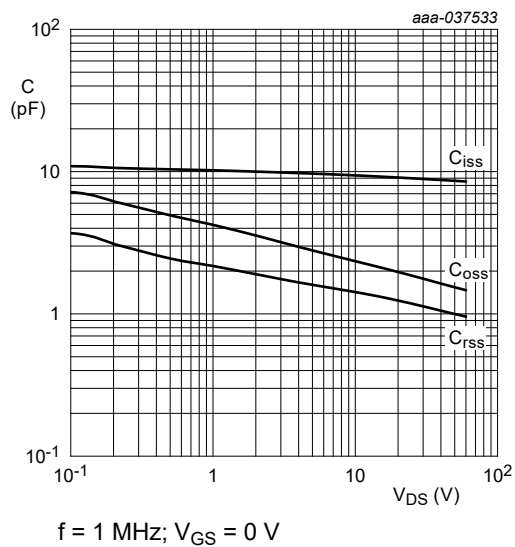


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

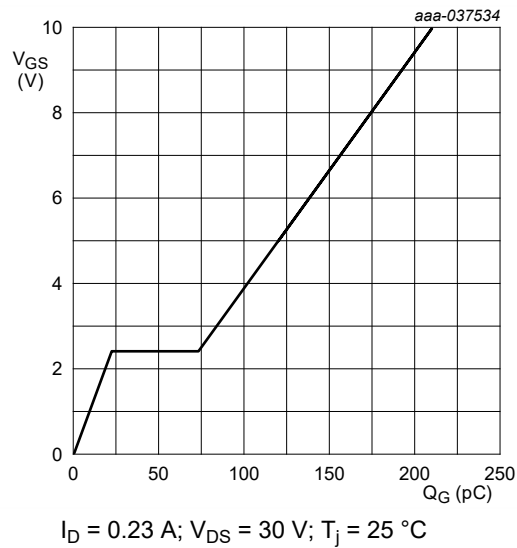


Fig. 14. Gate-source voltage as a function of gate charge; typical values

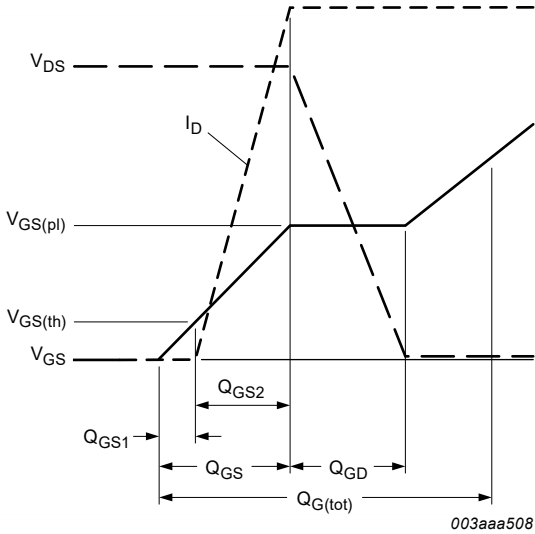


Fig. 15. Gate charge waveform definitions

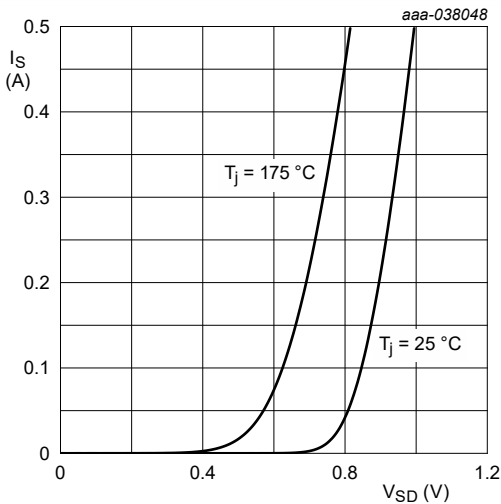


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

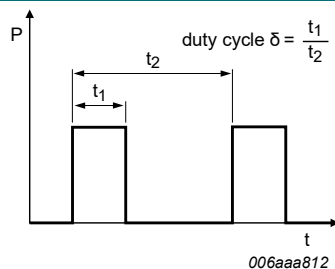


Fig. 17. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

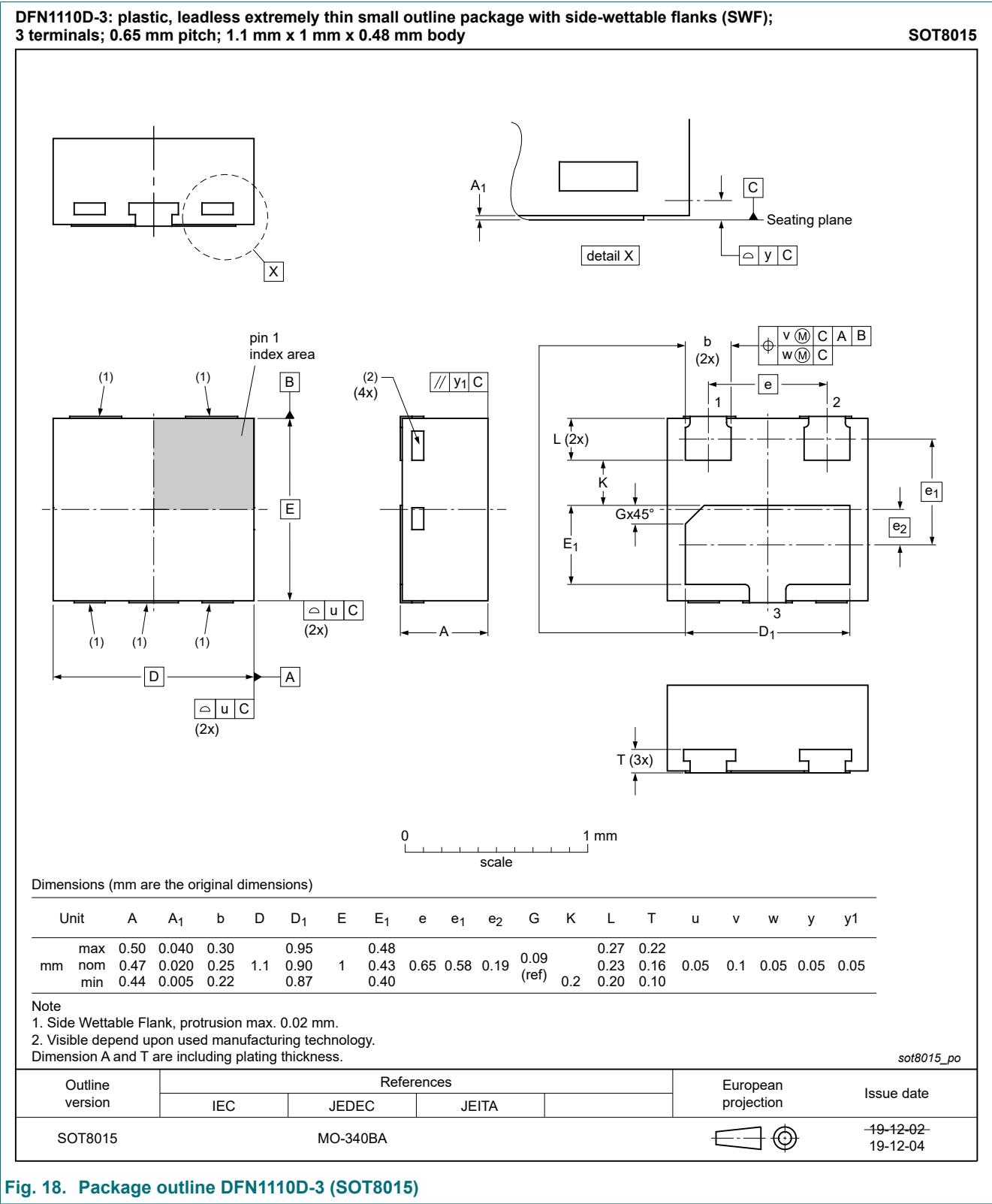


Fig. 18. Package outline DFN1110D-3 (SOT8015)

13. Soldering

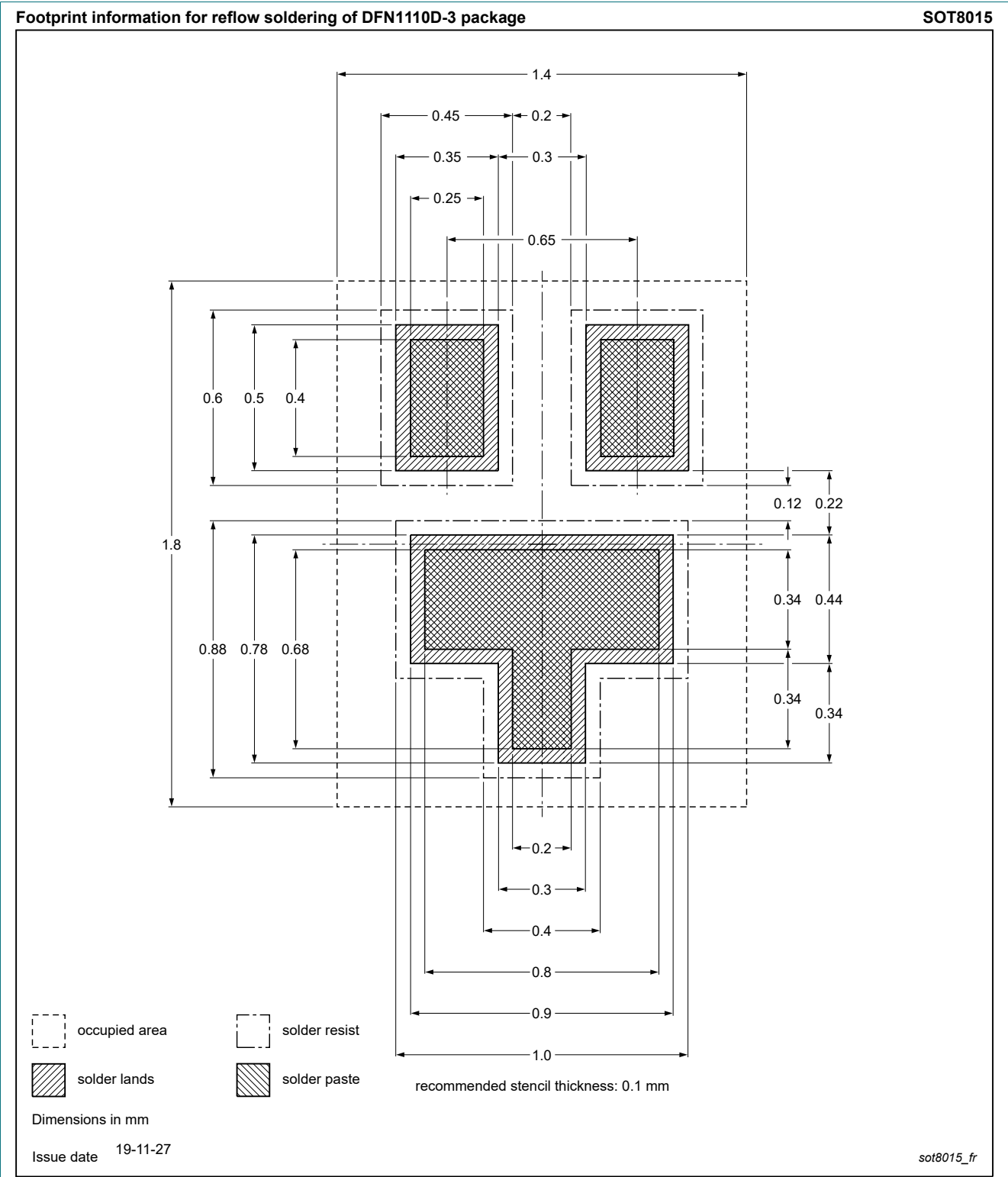


Fig. 19. Reflow soldering footprint for DFN1110D-3 (SOT8015)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BSS138AKQB-Q v.1	20240902	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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